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PATENT NUMBER and
ISSUE DATE

U.S. UTILITY Patent Application

APPL NUM 10015374	FILING DATE 12/12/2001	CLASS 257	SUBCLASS 685	GAU 28	EXAMINER William J.
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**APPLICANTS: Oh Kwang; Park Jong; Park Young; Min Byoung;

**CONTINUING DATA VERIFIED:

** FOREIGN APPLICATIONS VERIFIED:
REPUBLIC OF KOREA 2001-12326 03/09/2001

PG-PUB	DO NOT PUBLISH <input type="checkbox"/>	RESCIND <input type="checkbox"/>	ATTORNEY DOCKET NO W2K1070
Foreign priority claimed <input type="checkbox"/> yes <input type="checkbox"/> no			
35 USC 119 conditions met <input type="checkbox"/> yes <input type="checkbox"/> no			
Verified and Acknowledged Examiners's initials			
TITLE : Stacking structure of semiconductor chips and semiconductor package using it			

U.S. DEPT. OF COMM. / PAT. & TM-PTO-136L (Rev. 12-94)

NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED	
		Assistant Examiner	Total Claims <input type="checkbox"/> Print Claim for O.G.
ISSUE FEE		DRAWING	
Amount Due	Date Paid	Sheets Drawn	Figs. Drawn
		Print Fig.	
<input type="checkbox"/> TERMINAL DISCLAIMER		Primary Examiner	Application Examiner
		PREPARED FOR ISSUE	
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